

**IN THE CLAIMS**

Please amend the claims as follows.

For the Examiner's convenience, a list of all claims is included below.

1.-22. (Canceled)

23. (Canceled)

24. (Previously Presented) A system comprising:

a substrate comprising an electrical device;

a metallization pad disposed over the substrate;

a ball-limiting metallurgy disposed over the metallization pad, the ball-limiting metallurgy comprising:

a metal adhesion first layer disposed above and on the metallization pad;

a metal second layer disposed above and on the metal adhesion first layer;

a metal third layer disposed above and on the metal second layer;

an electrically conductive bump disposed above and on the metal third layer;

wherein at least one of the metal second layer and the metal third layer comprises copper; and

a flip-chip disposed over the ball-limiting metallurgy, wherein the flip-chip comprises a solder having a composition of about Sn37Pb, and wherein the electrically conductive bump comprises a solder having a composition of about Sn97Pb.

25-34. (Canceled)